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# Global Through-Hole Electronics Packaging Market Growth 2026-2032

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## Abstracts

The global Through-Hole Electronics Packaging market size is predicted to grow from US$ million in 2025 to US$ million in 2032; it is expected to grow at a CAGR of %from 2026 to 2032.

Through-Hole Electronics Packaging is the process by which the component leads are packed into the drilled holes on a bare printed circuit board. The Through-Hole Electronics Packaging offers number of advantages such as high-reliability, easy to solder/desolder and test and others. It also provides interconnections between upper and lower layers (vias) in non-plated hole technologies.

The global through-hole electronics packaging market refers to the market for packaging and assembly solutions that involve the use of through-hole technology (THT) in the production of electronic components. Through-hole technology is a traditional method of mounting electronic components on printed circuit boards (PCBs) by inserting leads or pins of the components through holes in the PCB and soldering them on the opposite side.

The through-hole electronics packaging market is driven by several factors:

Demand from various industries: Through-hole technology is commonly used in industries such as automotive, aerospace, industrial automation, telecommunications, and consumer electronics. The demand for through-hole electronics packaging stems from the need for reliable and robust connections in applications that require resistance to extreme conditions, vibration, and high mechanical stress.

Long-term reliability: Through-hole technology offers excellent mechanical strength and

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stability, making it suitable for applications that require long-term reliability, such as automotive electronics and critical industrial equipment. Through-hole components have higher resistance to mechanical stress compared to surface mount technology (SMT), providing enhanced durability and longevity.

Compatibility with legacy systems: Through-hole electronics packaging is often preferred for products that need to be compatible with existing or older systems. Many legacy systems, particularly in the aerospace and defense sectors, still rely on through-hole components. The through-hole technology allows for easy replacement, repair, and upgrading of electronic components.

Enhanced thermal dissipation: Through-hole components typically have thicker leads or pins compared to SMT components, which helps improve thermal dissipation and enables efficient heat transfer. This thermal advantage makes through-hole technology suitable for applications that generate significant heat, such as power electronics and high-performance computing.

Regulatory requirements: Certain industries, such as aerospace, defense, and medical, have strict regulatory requirements regarding reliability, safety, and quality. Through-hole technology, with its proven track record and ability to withstand harsh environmental conditions, often meets the stringent regulatory standards of these industries.

However, it is important to note that the through-hole electronics packaging market is witnessing a gradual shift towards surface mount technology due to the increasing demand for miniaturization, higher component density, and improved production efficiency. Surface mount technology offers advantages such as smaller PCB footprints, higher production speeds, and cost savings. Nevertheless, through-hole technology continues to find its application in specific industries and areas where its unique advantages outweigh the benefits of surface mount technology.

In conclusion, the global through-hole electronics packaging market is driven by the demand from various industries, the need for long-term reliability, compatibility with legacy systems, enhanced thermal dissipation, and regulatory requirements. While surface mount technology is gaining popularity, through-hole technology remains relevant and indispensable for specific applications that require robustness, durability, and compatibility with legacy systems.The global through-hole electronics packaging market refers to the market for packaging and assembly solutions that involve the use of through-hole technology (THT) in the production of electronic components. Through-

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LP Information, Inc. (LPI) ' newest research report, the ?Through-Hole Electronics Packaging Industry Forecast? looks at past sales and reviews total world Through-Hole Electronics Packaging sales in 2025, providing a comprehensive analysis by region and market sector of projected Through-Hole Electronics Packaging sales for 2026 through 2032. With Through-Hole Electronics Packaging sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US$ millions of the world Through-Hole Electronics Packaging industry.

This Insight Report provides a comprehensive analysis of the global Through-Hole Electronics Packaging landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Through-Hole Electronics Packaging portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms? unique position in an accelerating global Through-Hole Electronics Packaging market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Through-Hole Electronics Packaging and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Through-Hole Electronics Packaging.

This report presents a comprehensive overview, market shares, and growth opportunities of Through-Hole Electronics Packaging market by product type,

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application, key manufacturers and key regions and countries.

Segmentation by Type:

- Plastic
- Metal
- Glass
- Others

Segmentation by Application:

- Consumer Electronics
- Aerospace and Defense
- Automotive
- Telecommunications
- Others

This report also splits the market by region:

- Americas
  - United States
  - Canada
  - Mexico
  - Brazil
- APAC

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China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered

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from primary experts and analysing the company's coverage, product portfolio, its market penetration.

AMETEK, Inc.

Dordan Mfg

Dupont

Osram

The Plastiform Company

Kiva Container

Primex Plastics Corporation.

Quality Foam Packaging Inc

Ameson Packaging

Lithoflex, Inc.

UFP Technologies

Intel Corporation

STMicroelectronics

Advanced Micro Devices, Inc

SAMSUNG

GY Packaging

Taiwan Semiconductor

## Key Questions Addressed in this Report

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What is the 10-year outlook for the global Through-Hole Electronics Packaging market?

What factors are driving Through-Hole Electronics Packaging market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Through-Hole Electronics Packaging market opportunities vary by end market size?

How does Through-Hole Electronics Packaging break out by Type, by Application?

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# Contents

## 1 SCOPE OF THE REPORT

1.1 Market Introduction
1.2 Years Considered
1.3 Research Objectives
1.4 Market Research Methodology
1.5 Research Process and Data Source
1.6 Economic Indicators
1.7 Currency Considered
1.8 Market Estimation Caveats

## 2 EXECUTIVE SUMMARY

2.1 World Market Overview
  2.1.1 Global Through-Hole Electronics Packaging Annual Sales 2021-2032
  2.1.2 World Current & Future Analysis for Through-Hole Electronics Packaging by Geographic Region, 2021, 2025 & 2032
  2.1.3 World Current & Future Analysis for Through-Hole Electronics Packaging by Country/Region, 2021, 2025 & 2032
2.2 Through-Hole Electronics Packaging Segment by Type
  2.2.1 Plastic
  2.2.2 Metal
  2.2.3 Glass
  2.2.4 Others
  2.2.5 Through-Hole Electronics Packaging Sales by Type
    2.2.5.1 Global Through-Hole Electronics Packaging Sales Market Share by Type (2021-2026)
    2.2.5.2 Global Through-Hole Electronics Packaging Revenue and Market Share by Type (2021-2026)
    2.2.5.3 Global Through-Hole Electronics Packaging Sale Price by Type (2021-2026)
2.3 Through-Hole Electronics Packaging Segment by Application
  2.3.1 Consumer Electronics
  2.3.2 Aerospace and Defense
  2.3.3 Automotive
  2.3.4 Telecommunications
  2.3.5 Others
  2.3.6 Through-Hole Electronics Packaging Sales by Application

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2.3.6.1 Global Through-Hole Electronics Packaging Sale Market Share by Application (2021-2026)
2.3.6.2 Global Through-Hole Electronics Packaging Revenue and Market Share by Application (2021-2026)
2.3.6.3 Global Through-Hole Electronics Packaging Sale Price by Application (2021-2026)

## 3 GLOBAL BY COMPANY

3.1 Global Through-Hole Electronics Packaging Breakdown Data by Company
3.1.1 Global Through-Hole Electronics Packaging Annual Sales by Company (2021-2026)
3.1.2 Global Through-Hole Electronics Packaging Sales Market Share by Company (2021-2026)
3.2 Global Through-Hole Electronics Packaging Annual Revenue by Company (2021-2026)
3.2.1 Global Through-Hole Electronics Packaging Revenue by Company (2021-2026)
3.2.2 Global Through-Hole Electronics Packaging Revenue Market Share by Company (2021-2026)
3.3 Global Through-Hole Electronics Packaging Sale Price by Company
3.4 Key Manufacturers Through-Hole Electronics Packaging Producing Area Distribution, Sales Area, Product Type
3.4.1 Key Manufacturers Through-Hole Electronics Packaging Product Location Distribution
3.4.2 Players Through-Hole Electronics Packaging Products Offered
3.5 Market Concentration Rate Analysis
3.5.1 Competition Landscape Analysis
3.5.2 Concentration Ratio (CR3, CR5 and CR10) & (2024-2026)
3.6 New Products and Potential Entrants
3.7 Market M&A Activity & Strategy

## 4 WORLD HISTORIC REVIEW FOR THROUGH-HOLE ELECTRONICS PACKAGING BY GEOGRAPHIC REGION

4.1 World Historic Through-Hole Electronics Packaging Market Size by Geographic Region (2021-2026)
4.1.1 Global Through-Hole Electronics Packaging Annual Sales by Geographic Region (2021-2026)
4.1.2 Global Through-Hole Electronics Packaging Annual Revenue by Geographic

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Region (2021-2026)
4.2 World Historic Through-Hole Electronics Packaging Market Size by Country/Region (2021-2026)
4.2.1 Global Through-Hole Electronics Packaging Annual Sales by Country/Region (2021-2026)
4.2.2 Global Through-Hole Electronics Packaging Annual Revenue by Country/Region (2021-2026)
4.3 Americas Through-Hole Electronics Packaging Sales Growth
4.4 APAC Through-Hole Electronics Packaging Sales Growth
4.5 Europe Through-Hole Electronics Packaging Sales Growth
4.6 Middle East & Africa Through-Hole Electronics Packaging Sales Growth

**5 AMERICAS**

5.1 Americas Through-Hole Electronics Packaging Sales by Country
5.1.1 Americas Through-Hole Electronics Packaging Sales by Country (2021-2026)
5.1.2 Americas Through-Hole Electronics Packaging Revenue by Country (2021-2026)
5.2 Americas Through-Hole Electronics Packaging Sales by Type (2021-2026)
5.3 Americas Through-Hole Electronics Packaging Sales by Application (2021-2026)
5.4 United States
5.5 Canada
5.6 Mexico
5.7 Brazil

**6 APAC**

6.1 APAC Through-Hole Electronics Packaging Sales by Region
6.1.1 APAC Through-Hole Electronics Packaging Sales by Region (2021-2026)
6.1.2 APAC Through-Hole Electronics Packaging Revenue by Region (2021-2026)
6.2 APAC Through-Hole Electronics Packaging Sales by Type (2021-2026)
6.3 APAC Through-Hole Electronics Packaging Sales by Application (2021-2026)
6.4 China
6.5 Japan
6.6 South Korea
6.7 Southeast Asia
6.8 India
6.9 Australia
6.10 China Taiwan

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info@marketpublishers.com

## 7 EUROPE

7.1 Europe Through-Hole Electronics Packaging by Country
7.1.1 Europe Through-Hole Electronics Packaging Sales by Country (2021-2026)
7.1.2 Europe Through-Hole Electronics Packaging Revenue by Country (2021-2026)
7.2 Europe Through-Hole Electronics Packaging Sales by Type (2021-2026)
7.3 Europe Through-Hole Electronics Packaging Sales by Application (2021-2026)
7.4 Germany
7.5 France
7.6 UK
7.7 Italy
7.8 Russia

## 8 MIDDLE EAST & AFRICA

8.1 Middle East & Africa Through-Hole Electronics Packaging by Country
8.1.1 Middle East & Africa Through-Hole Electronics Packaging Sales by Country (2021-2026)
8.1.2 Middle East & Africa Through-Hole Electronics Packaging Revenue by Country (2021-2026)
8.2 Middle East & Africa Through-Hole Electronics Packaging Sales by Type (2021-2026)
8.3 Middle East & Africa Through-Hole Electronics Packaging Sales by Application (2021-2026)
8.4 Egypt
8.5 South Africa
8.6 Israel
8.7 Turkey
8.8 GCC Countries

## 9 MARKET DRIVERS, CHALLENGES AND TRENDS

9.1 Market Drivers & Growth Opportunities
9.2 Market Challenges & Risks
9.3 Industry Trends

## 10 MANUFACTURING COST STRUCTURE ANALYSIS

10.1 Raw Material and Suppliers

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info@marketpublishers.com

10.2 Manufacturing Cost Structure Analysis of Through-Hole Electronics Packaging
10.3 Manufacturing Process Analysis of Through-Hole Electronics Packaging
10.4 Industry Chain Structure of Through-Hole Electronics Packaging

**11 MARKETING, DISTRIBUTORS AND CUSTOMER**

11.1 Sales Channel
  11.1.1 Direct Channels
  11.1.2 Indirect Channels
11.2 Through-Hole Electronics Packaging Distributors
11.3 Through-Hole Electronics Packaging Customer

**12 WORLD FORECAST REVIEW FOR THROUGH-HOLE ELECTRONICS PACKAGING BY GEOGRAPHIC REGION**

12.1 Global Through-Hole Electronics Packaging Market Size Forecast by Region
  12.1.1 Global Through-Hole Electronics Packaging Forecast by Region (2027-2032)
  12.1.2 Global Through-Hole Electronics Packaging Annual Revenue Forecast by Region (2027-2032)
12.2 Americas Forecast by Country (2027-2032)
12.3 APAC Forecast by Region (2027-2032)
12.4 Europe Forecast by Country (2027-2032)
12.5 Middle East & Africa Forecast by Country (2027-2032)
12.6 Global Through-Hole Electronics Packaging Forecast by Type (2027-2032)
12.7 Global Through-Hole Electronics Packaging Forecast by Application (2027-2032)

**13 KEY PLAYERS ANALYSIS**

13.1 AMETEK, Inc.
  13.1.1 AMETEK, Inc. Company Information
  13.1.2 AMETEK, Inc. Through-Hole Electronics Packaging Product Portfolios and Specifications
  13.1.3 AMETEK, Inc. Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
  13.1.4 AMETEK, Inc. Main Business Overview
  13.1.5 AMETEK, Inc. Latest Developments
13.2 Dordan Mfg
  13.2.1 Dordan Mfg Company Information
  13.2.2 Dordan Mfg Through-Hole Electronics Packaging Product Portfolios and

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Specifications
13.2.3 Dordan Mfg Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.2.4 Dordan Mfg Main Business Overview
13.2.5 Dordan Mfg Latest Developments
13.3 Dupont
13.3.1 Dupont Company Information
13.3.2 Dupont Through-Hole Electronics Packaging Product Portfolios and Specifications
13.3.3 Dupont Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.3.4 Dupont Main Business Overview
13.3.5 Dupont Latest Developments
13.4 Osram
13.4.1 Osram Company Information
13.4.2 Osram Through-Hole Electronics Packaging Product Portfolios and Specifications
13.4.3 Osram Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.4.4 Osram Main Business Overview
13.4.5 Osram Latest Developments
13.5 The Plastiform Company
13.5.1 The Plastiform Company Company Information
13.5.2 The Plastiform Company Through-Hole Electronics Packaging Product Portfolios and Specifications
13.5.3 The Plastiform Company Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.5.4 The Plastiform Company Main Business Overview
13.5.5 The Plastiform Company Latest Developments
13.6 Kiva Container
13.6.1 Kiva Container Company Information
13.6.2 Kiva Container Through-Hole Electronics Packaging Product Portfolios and Specifications
13.6.3 Kiva Container Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.6.4 Kiva Container Main Business Overview
13.6.5 Kiva Container Latest Developments
13.7 Primex Plastics Corporation.
13.7.1 Primex Plastics Corporation. Company Information

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info@marketpublishers.com

13.7.2 Primex Plastics Corporation. Through-Hole Electronics Packaging Product Portfolios and Specifications
13.7.3 Primex Plastics Corporation. Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.7.4 Primex Plastics Corporation. Main Business Overview
13.7.5 Primex Plastics Corporation. Latest Developments
13.8 Quality Foam Packaging Inc
13.8.1 Quality Foam Packaging Inc Company Information
13.8.2 Quality Foam Packaging Inc Through-Hole Electronics Packaging Product Portfolios and Specifications
13.8.3 Quality Foam Packaging Inc Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.8.4 Quality Foam Packaging Inc Main Business Overview
13.8.5 Quality Foam Packaging Inc Latest Developments
13.9 Ameson Packaging
13.9.1 Ameson Packaging Company Information
13.9.2 Ameson Packaging Through-Hole Electronics Packaging Product Portfolios and Specifications
13.9.3 Ameson Packaging Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.9.4 Ameson Packaging Main Business Overview
13.9.5 Ameson Packaging Latest Developments
13.10 Lithoflex, Inc.
13.10.1 Lithoflex, Inc. Company Information
13.10.2 Lithoflex, Inc. Through-Hole Electronics Packaging Product Portfolios and Specifications
13.10.3 Lithoflex, Inc. Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.10.4 Lithoflex, Inc. Main Business Overview
13.10.5 Lithoflex, Inc. Latest Developments
13.11 UFP Technologies
13.11.1 UFP Technologies Company Information
13.11.2 UFP Technologies Through-Hole Electronics Packaging Product Portfolios and Specifications
13.11.3 UFP Technologies Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.11.4 UFP Technologies Main Business Overview
13.11.5 UFP Technologies Latest Developments
13.12 Intel Corporation

+357 96 030922
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13.12.1 Intel Corporation Company Information
13.12.2 Intel Corporation Through-Hole Electronics Packaging Product Portfolios and Specifications
13.12.3 Intel Corporation Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.12.4 Intel Corporation Main Business Overview
13.12.5 Intel Corporation Latest Developments
13.13 STMicroelectronics
13.13.1 STMicroelectronics Company Information
13.13.2 STMicroelectronics Through-Hole Electronics Packaging Product Portfolios and Specifications
13.13.3 STMicroelectronics Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.13.4 STMicroelectronics Main Business Overview
13.13.5 STMicroelectronics Latest Developments
13.14 Advanced Micro Devices, Inc
13.14.1 Advanced Micro Devices, Inc Company Information
13.14.2 Advanced Micro Devices, Inc Through-Hole Electronics Packaging Product Portfolios and Specifications
13.14.3 Advanced Micro Devices, Inc Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.14.4 Advanced Micro Devices, Inc Main Business Overview
13.14.5 Advanced Micro Devices, Inc Latest Developments
13.15 SAMSUNG
13.15.1 SAMSUNG Company Information
13.15.2 SAMSUNG Through-Hole Electronics Packaging Product Portfolios and Specifications
13.15.3 SAMSUNG Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.15.4 SAMSUNG Main Business Overview
13.15.5 SAMSUNG Latest Developments
13.16 GY Packaging
13.16.1 GY Packaging Company Information
13.16.2 GY Packaging Through-Hole Electronics Packaging Product Portfolios and Specifications
13.16.3 GY Packaging Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.16.4 GY Packaging Main Business Overview
13.16.5 GY Packaging Latest Developments

+357 96 030922
info@marketpublishers.com

13.17 Taiwan Semiconductor
13.17.1 Taiwan Semiconductor Company Information
13.17.2 Taiwan Semiconductor Through-Hole Electronics Packaging Product Portfolios and Specifications
13.17.3 Taiwan Semiconductor Through-Hole Electronics Packaging Sales, Revenue, Price and Gross Margin (2021-2026)
13.17.4 Taiwan Semiconductor Main Business Overview
13.17.5 Taiwan Semiconductor Latest Developments

**14 RESEARCH FINDINGS AND CONCLUSION**

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# List Of Tables

## LIST OF TABLES

Table 1. Through-Hole Electronics Packaging Annual Sales CAGR by Geographic Region (2021, 2025 & 2032) & ($ millions)
Table 2. Through-Hole Electronics Packaging Annual Sales CAGR by Country/Region (2021, 2025 & 2032) & ($ millions)
Table 3. Major Players of Plastic
Table 4. Major Players of Metal
Table 5. Major Players of Glass
Table 6. Major Players of Others
Table 7. Global Through-Hole Electronics Packaging Sales by Type (2021-2026) & (K Units)
Table 8. Global Through-Hole Electronics Packaging Sales Market Share by Type (2021-2026)
Table 9. Global Through-Hole Electronics Packaging Revenue by Type (2021-2026) & ($ million)
Table 10. Global Through-Hole Electronics Packaging Revenue Market Share by Type (2021-2026)
Table 11. Global Through-Hole Electronics Packaging Sale Price by Type (2021-2026) & (US$/Unit)
Table 12. Global Through-Hole Electronics Packaging Sale by Application (2021-2026) & (K Units)
Table 13. Global Through-Hole Electronics Packaging Sale Market Share by Application (2021-2026)
Table 14. Global Through-Hole Electronics Packaging Revenue by Application (2021-2026) & ($ million)
Table 15. Global Through-Hole Electronics Packaging Revenue Market Share by Application (2021-2026)
Table 16. Global Through-Hole Electronics Packaging Sale Price by Application (2021-2026) & (US$/Unit)
Table 17. Global Through-Hole Electronics Packaging Sales by Company (2021-2026) & (K Units)
Table 18. Global Through-Hole Electronics Packaging Sales Market Share by Company (2021-2026)
Table 19. Global Through-Hole Electronics Packaging Revenue by Company (2021-2026) & ($ millions)
Table 20. Global Through-Hole Electronics Packaging Revenue Market Share by

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info@marketpublishers.com

Company (2021-2026)
Table 21. Global Through-Hole Electronics Packaging Sale Price by Company (2021-2026) & (US$/Unit)
Table 22. Key Manufacturers Through-Hole Electronics Packaging Producing Area Distribution and Sales Area
Table 23. Players Through-Hole Electronics Packaging Products Offered
Table 24. Through-Hole Electronics Packaging Concentration Ratio (CR3, CR5 and CR10) & (2024-2026)
Table 25. New Products and Potential Entrants
Table 26. Market M&A Activity & Strategy
Table 27. Global Through-Hole Electronics Packaging Sales by Geographic Region (2021-2026) & (K Units)
Table 28. Global Through-Hole Electronics Packaging Sales Market Share Geographic Region (2021-2026)
Table 29. Global Through-Hole Electronics Packaging Revenue by Geographic Region (2021-2026) & ($ millions)
Table 30. Global Through-Hole Electronics Packaging Revenue Market Share by Geographic Region (2021-2026)
Table 31. Global Through-Hole Electronics Packaging Sales by Country/Region (2021-2026) & (K Units)
Table 32. Global Through-Hole Electronics Packaging Sales Market Share by Country/Region (2021-2026)
Table 33. Global Through-Hole Electronics Packaging Revenue by Country/Region (2021-2026) & ($ millions)
Table 34. Global Through-Hole Electronics Packaging Revenue Market Share by Country/Region (2021-2026)
Table 35. Americas Through-Hole Electronics Packaging Sales by Country (2021-2026) & (K Units)
Table 36. Americas Through-Hole Electronics Packaging Sales Market Share by Country (2021-2026)
Table 37. Americas Through-Hole Electronics Packaging Revenue by Country (2021-2026) & ($ millions)
Table 38. Americas Through-Hole Electronics Packaging Sales by Type (2021-2026) & (K Units)
Table 39. Americas Through-Hole Electronics Packaging Sales by Application (2021-2026) & (K Units)
Table 40. APAC Through-Hole Electronics Packaging Sales by Region (2021-2026) & (K Units)
Table 41. APAC Through-Hole Electronics Packaging Sales Market Share by Region

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info@marketpublishers.com

(2021-2026)
Table 42. APAC Through-Hole Electronics Packaging Revenue by Region (2021-2026) & ($ millions)
Table 43. APAC Through-Hole Electronics Packaging Sales by Type (2021-2026) & (K Units)
Table 44. APAC Through-Hole Electronics Packaging Sales by Application (2021-2026) & (K Units)
Table 45. Europe Through-Hole Electronics Packaging Sales by Country (2021-2026) & (K Units)
Table 46. Europe Through-Hole Electronics Packaging Revenue by Country (2021-2026) & ($ millions)
Table 47. Europe Through-Hole Electronics Packaging Sales by Type (2021-2026) & (K Units)
Table 48. Europe Through-Hole Electronics Packaging Sales by Application (2021-2026) & (K Units)
Table 49. Middle East & Africa Through-Hole Electronics Packaging Sales by Country (2021-2026) & (K Units)
Table 50. Middle East & Africa Through-Hole Electronics Packaging Revenue Market Share by Country (2021-2026)
Table 51. Middle East & Africa Through-Hole Electronics Packaging Sales by Type (2021-2026) & (K Units)
Table 52. Middle East & Africa Through-Hole Electronics Packaging Sales by Application (2021-2026) & (K Units)
Table 53. Key Market Drivers & Growth Opportunities of Through-Hole Electronics Packaging
Table 54. Key Market Challenges & Risks of Through-Hole Electronics Packaging
Table 55. Key Industry Trends of Through-Hole Electronics Packaging
Table 56. Through-Hole Electronics Packaging Raw Material
Table 57. Key Suppliers of Raw Materials
Table 58. Through-Hole Electronics Packaging Distributors List
Table 59. Through-Hole Electronics Packaging Customer List
Table 60. Global Through-Hole Electronics Packaging Sales Forecast by Region (2027-2032) & (K Units)
Table 61. Global Through-Hole Electronics Packaging Revenue Forecast by Region (2027-2032) & ($ millions)
Table 62. Americas Through-Hole Electronics Packaging Sales Forecast by Country (2027-2032) & (K Units)
Table 63. Americas Through-Hole Electronics Packaging Annual Revenue Forecast by Country (2027-2032) & ($ millions)

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Table 64. APAC Through-Hole Electronics Packaging Sales Forecast by Region (2027-2032) & (K Units)
Table 65. APAC Through-Hole Electronics Packaging Annual Revenue Forecast by Region (2027-2032) & ($ millions)
Table 66. Europe Through-Hole Electronics Packaging Sales Forecast by Country (2027-2032) & (K Units)
Table 67. Europe Through-Hole Electronics Packaging Revenue Forecast by Country (2027-2032) & ($ millions)
Table 68. Middle East & Africa Through-Hole Electronics Packaging Sales Forecast by Country (2027-2032) & (K Units)
Table 69. Middle East & Africa Through-Hole Electronics Packaging Revenue Forecast by Country (2027-2032) & ($ millions)
Table 70. Global Through-Hole Electronics Packaging Sales Forecast by Type (2027-2032) & (K Units)
Table 71. Global Through-Hole Electronics Packaging Revenue Forecast by Type (2027-2032) & ($ millions)
Table 72. Global Through-Hole Electronics Packaging Sales Forecast by Application (2027-2032) & (K Units)
Table 73. Global Through-Hole Electronics Packaging Revenue Forecast by Application (2027-2032) & ($ millions)
Table 74. AMETEK, Inc. Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 75. AMETEK, Inc. Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 76. AMETEK, Inc. Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 77. AMETEK, Inc. Main Business
Table 78. AMETEK, Inc. Latest Developments
Table 79. Dordan Mfg Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 80. Dordan Mfg Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 81. Dordan Mfg Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 82. Dordan Mfg Main Business
Table 83. Dordan Mfg Latest Developments
Table 84. Dupont Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 85. Dupont Through-Hole Electronics Packaging Product Portfolios and

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Specifications
Table 86. Dupont Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 87. Dupont Main Business
Table 88. Dupont Latest Developments
Table 89. Osram Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 90. Osram Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 91. Osram Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 92. Osram Main Business
Table 93. Osram Latest Developments
Table 94. The Plastiform Company Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 95. The Plastiform Company Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 96. The Plastiform Company Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 97. The Plastiform Company Main Business
Table 98. The Plastiform Company Latest Developments
Table 99. Kiva Container Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 100. Kiva Container Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 101. Kiva Container Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 102. Kiva Container Main Business
Table 103. Kiva Container Latest Developments
Table 104. Primex Plastics Corporation. Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 105. Primex Plastics Corporation. Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 106. Primex Plastics Corporation. Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 107. Primex Plastics Corporation. Main Business
Table 108. Primex Plastics Corporation. Latest Developments
Table 109. Quality Foam Packaging Inc Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors

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Table 110. Quality Foam Packaging Inc Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 111. Quality Foam Packaging Inc Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 112. Quality Foam Packaging Inc Main Business
Table 113. Quality Foam Packaging Inc Latest Developments
Table 114. Ameson Packaging Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 115. Ameson Packaging Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 116. Ameson Packaging Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 117. Ameson Packaging Main Business
Table 118. Ameson Packaging Latest Developments
Table 119. Lithoflex, Inc. Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 120. Lithoflex, Inc. Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 121. Lithoflex, Inc. Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 122. Lithoflex, Inc. Main Business
Table 123. Lithoflex, Inc. Latest Developments
Table 124. UFP Technologies Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 125. UFP Technologies Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 126. UFP Technologies Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 127. UFP Technologies Main Business
Table 128. UFP Technologies Latest Developments
Table 129. Intel Corporation Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 130. Intel Corporation Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 131. Intel Corporation Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 132. Intel Corporation Main Business
Table 133. Intel Corporation Latest Developments
Table 134. STMicroelectronics Basic Information, Through-Hole Electronics Packaging

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Manufacturing Base, Sales Area and Its Competitors
Table 135. STMicroelectronics Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 136. STMicroelectronics Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 137. STMicroelectronics Main Business
Table 138. STMicroelectronics Latest Developments
Table 139. Advanced Micro Devices, Inc Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 140. Advanced Micro Devices, Inc Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 141. Advanced Micro Devices, Inc Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 142. Advanced Micro Devices, Inc Main Business
Table 143. Advanced Micro Devices, Inc Latest Developments
Table 144. SAMSUNG Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 145. SAMSUNG Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 146. SAMSUNG Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 147. SAMSUNG Main Business
Table 148. SAMSUNG Latest Developments
Table 149. GY Packaging Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 150. GY Packaging Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 151. GY Packaging Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 152. GY Packaging Main Business
Table 153. GY Packaging Latest Developments
Table 154. Taiwan Semiconductor Basic Information, Through-Hole Electronics Packaging Manufacturing Base, Sales Area and Its Competitors
Table 155. Taiwan Semiconductor Through-Hole Electronics Packaging Product Portfolios and Specifications
Table 156. Taiwan Semiconductor Through-Hole Electronics Packaging Sales (K Units), Revenue ($ Million), Price (US$/Unit) and Gross Margin (2021-2026)
Table 157. Taiwan Semiconductor Main Business
Table 158. Taiwan Semiconductor Latest Developments

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# List Of Figures

## LIST OF FIGURES

Figure 1. Picture of Through-Hole Electronics Packaging
Figure 2. Through-Hole Electronics Packaging Report Years Considered
Figure 3. Research Objectives
Figure 4. Research Methodology
Figure 5. Research Process and Data Source
Figure 6. Global Through-Hole Electronics Packaging Sales Growth Rate 2021-2032 (K Units)
Figure 7. Global Through-Hole Electronics Packaging Revenue Growth Rate 2021-2032 ($ millions)
Figure 8. Through-Hole Electronics Packaging Sales by Geographic Region (2021, 2025 & 2032) & ($ millions)
Figure 9. Through-Hole Electronics Packaging Sales Market Share by Country/Region (2025)
Figure 10. Through-Hole Electronics Packaging Sales Market Share by Country/Region (2021, 2025 & 2032)
Figure 11. Product Picture of Plastic
Figure 12. Product Picture of Metal
Figure 13. Product Picture of Glass
Figure 14. Product Picture of Others
Figure 15. Global Through-Hole Electronics Packaging Sales Market Share by Type in 2026
Figure 16. Global Through-Hole Electronics Packaging Revenue Market Share by Type (2021-2026)
Figure 17. Through-Hole Electronics Packaging Consumed in Consumer Electronics
Figure 18. Global Through-Hole Electronics Packaging Market: Consumer Electronics (2021-2026) & (K Units)
Figure 19. Through-Hole Electronics Packaging Consumed in Aerospace and Defense
Figure 20. Global Through-Hole Electronics Packaging Market: Aerospace and Defense (2021-2026) & (K Units)
Figure 21. Through-Hole Electronics Packaging Consumed in Automotive
Figure 22. Global Through-Hole Electronics Packaging Market: Automotive (2021-2026) & (K Units)
Figure 23. Through-Hole Electronics Packaging Consumed in Telecommunications
Figure 24. Global Through-Hole Electronics Packaging Market: Telecommunications (2021-2026) & (K Units)

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Figure 25. Through-Hole Electronics Packaging Consumed in Others
Figure 26. Global Through-Hole Electronics Packaging Market: Others (2021-2026) & (K Units)
Figure 27. Global Through-Hole Electronics Packaging Sale Market Share by Application (2025)
Figure 28. Global Through-Hole Electronics Packaging Revenue Market Share by Application in 2026
Figure 29. Through-Hole Electronics Packaging Sales by Company in 2026 (K Units)
Figure 30. Global Through-Hole Electronics Packaging Sales Market Share by Company in 2026
Figure 31. Through-Hole Electronics Packaging Revenue by Company in 2026 ($ millions)
Figure 32. Global Through-Hole Electronics Packaging Revenue Market Share by Company in 2026
Figure 33. Global Through-Hole Electronics Packaging Sales Market Share by Geographic Region (2021-2026)
Figure 34. Global Through-Hole Electronics Packaging Revenue Market Share by Geographic Region in 2026
Figure 35. Americas Through-Hole Electronics Packaging Sales 2021-2026 (K Units)
Figure 36. Americas Through-Hole Electronics Packaging Revenue 2021-2026 ($ millions)
Figure 37. APAC Through-Hole Electronics Packaging Sales 2021-2026 (K Units)
Figure 38. APAC Through-Hole Electronics Packaging Revenue 2021-2026 ($ millions)
Figure 39. Europe Through-Hole Electronics Packaging Sales 2021-2026 (K Units)
Figure 40. Europe Through-Hole Electronics Packaging Revenue 2021-2026 ($ millions)
Figure 41. Middle East & Africa Through-Hole Electronics Packaging Sales 2021-2026 (K Units)
Figure 42. Middle East & Africa Through-Hole Electronics Packaging Revenue 2021-2026 ($ millions)
Figure 43. Americas Through-Hole Electronics Packaging Sales Market Share by Country in 2026
Figure 44. Americas Through-Hole Electronics Packaging Revenue Market Share by Country (2021-2026)
Figure 45. Americas Through-Hole Electronics Packaging Sales Market Share by Type (2021-2026)
Figure 46. Americas Through-Hole Electronics Packaging Sales Market Share by Application (2021-2026)
Figure 47. United States Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)

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Figure 48. Canada Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 49. Mexico Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 50. Brazil Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 51. APAC Through-Hole Electronics Packaging Sales Market Share by Region in 2026
Figure 52. APAC Through-Hole Electronics Packaging Revenue Market Share by Region (2021-2026)
Figure 53. APAC Through-Hole Electronics Packaging Sales Market Share by Type (2021-2026)
Figure 54. APAC Through-Hole Electronics Packaging Sales Market Share by Application (2021-2026)
Figure 55. China Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 56. Japan Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 57. South Korea Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 58. Southeast Asia Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 59. India Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 60. Australia Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 61. China Taiwan Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 62. Europe Through-Hole Electronics Packaging Sales Market Share by Country in 2026
Figure 63. Europe Through-Hole Electronics Packaging Revenue Market Share by Country (2021-2026)
Figure 64. Europe Through-Hole Electronics Packaging Sales Market Share by Type (2021-2026)
Figure 65. Europe Through-Hole Electronics Packaging Sales Market Share by Application (2021-2026)
Figure 66. Germany Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 67. France Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($

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millions)
Figure 68. UK Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 69. Italy Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 70. Russia Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 71. Middle East & Africa Through-Hole Electronics Packaging Sales Market Share by Country (2021-2026)
Figure 72. Middle East & Africa Through-Hole Electronics Packaging Sales Market Share by Type (2021-2026)
Figure 73. Middle East & Africa Through-Hole Electronics Packaging Sales Market Share by Application (2021-2026)
Figure 74. Egypt Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 75. South Africa Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 76. Israel Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 77. Turkey Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 78. GCC Countries Through-Hole Electronics Packaging Revenue Growth 2021-2026 ($ millions)
Figure 79. Manufacturing Cost Structure Analysis of Through-Hole Electronics Packaging in 2026
Figure 80. Manufacturing Process Analysis of Through-Hole Electronics Packaging
Figure 81. Industry Chain Structure of Through-Hole Electronics Packaging
Figure 82. Channels of Distribution
Figure 83. Global Through-Hole Electronics Packaging Sales Market Forecast by Region (2027-2032)
Figure 84. Global Through-Hole Electronics Packaging Revenue Market Share Forecast by Region (2027-2032)
Figure 85. Global Through-Hole Electronics Packaging Sales Market Share Forecast by Type (2027-2032)
Figure 86. Global Through-Hole Electronics Packaging Revenue Market Share Forecast by Type (2027-2032)
Figure 87. Global Through-Hole Electronics Packaging Sales Market Share Forecast by Application (2027-2032)
Figure 88. Global Through-Hole Electronics Packaging Revenue Market Share Forecast

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